

Title (en)  
Heat-dissipating device

Title (de)  
Wärmeableitvorrichtung

Title (fr)  
Dispositif dissipateur de chaleur

Publication  
**EP 1498684 A1 20050119 (EN)**

Application  
**EP 03254436 A 20030714**

Priority  
EP 03254436 A 20030714

Abstract (en)  
A heat-dissipating device includes a hollow housing adapted to contact a heat source (3, 3') and for receiving a heat-conducting fluid (12) therein, a heat-conducting member (22) contacting the heat-conducting fluid (12), and a heat-dissipating fin unit driven to move within an ambient fluid so as to dissipate heat from the fin unit to the ambient fluid. <IMAGE>

IPC 1-7  
**F28F 13/00**

IPC 8 full level  
**F28D 11/02** (2006.01); **F28D 11/06** (2006.01); **F28F 13/00** (2006.01)

CPC (source: EP)  
**F28D 11/02** (2013.01); **F28D 11/06** (2013.01); **F28F 3/12** (2013.01); **F28D 2021/0028** (2013.01); **F28F 2250/08** (2013.01)

Citation (search report)  

- [Y] US 6230788 B1 20010515 - CHOO KOK FAH [SG], et al
- [Y] FR 1460908 A 19660304 - DEV IND PROCLEM SOC ET
- [A] DATABASE WPI Section PQ Week 197846, Derwent World Patents Index; Class Q78, AN 1978-K1675A, XP002264376
- [A] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 10 31 October 1997 (1997-10-31)
- [A] PATENT ABSTRACTS OF JAPAN vol. 015, no. 014 (E - 1022) 11 January 1991 (1991-01-11)
- [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 12 31 October 1998 (1998-10-31)

Cited by  
DE102004028410A1; CN107087384A

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

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